



Objectives for 100 Gb/s shorter-reach PMDs

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IEEE 802.3 100 Gb/s Wavelength Short
Reach PHYs Study Group



Background-1

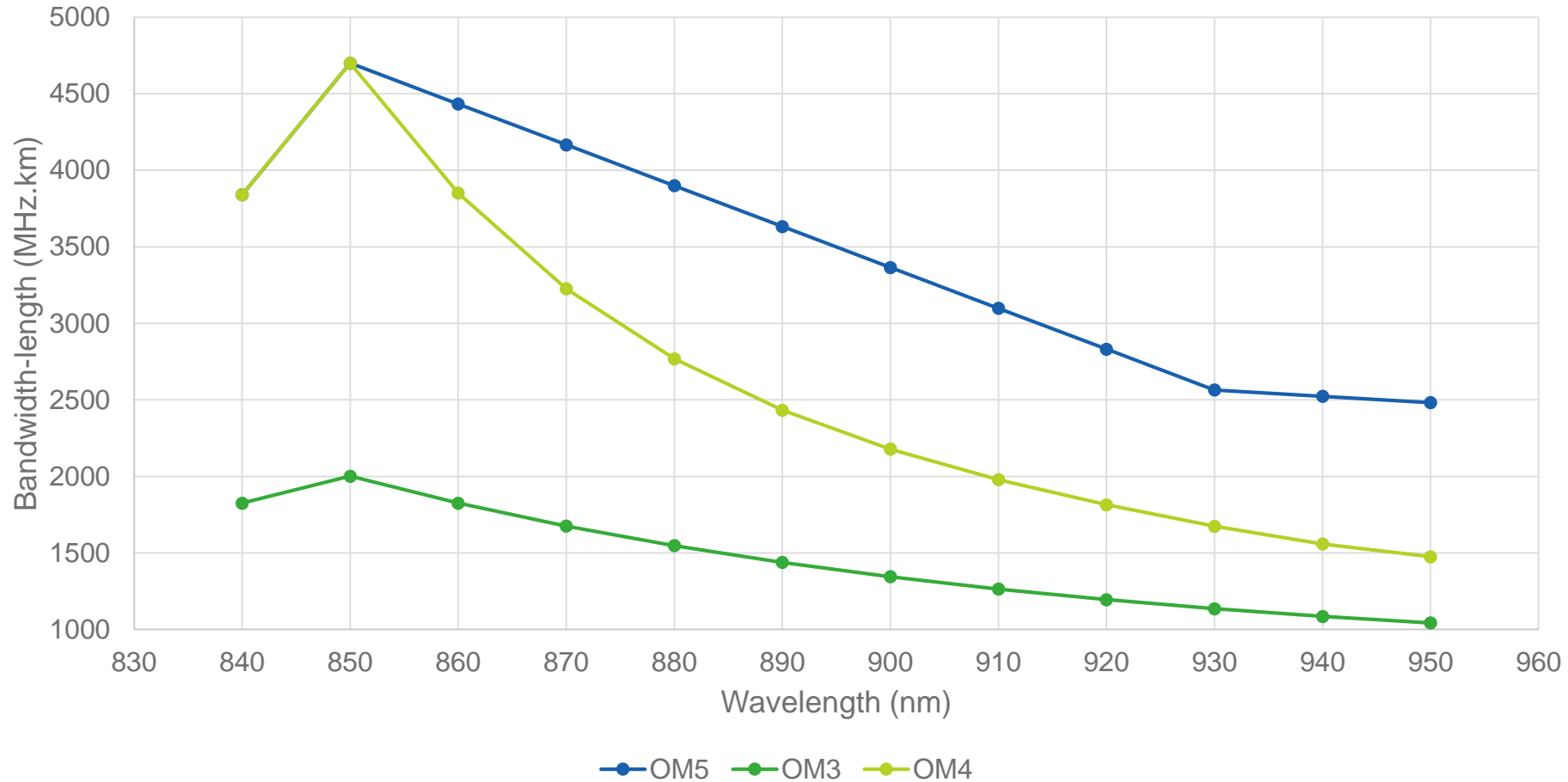
- [lewis_100GSR_01_0120.pdf](#) proposed 2 objectives:
 - Objective for MMF backwards compatibility and intra Data Center reach
 - The adopted objective of 50 m on 1 pair of MMF is enough for some data centers, but not all.
 - No mention of backwards compatibility with 50G-SR or 25G-SR in the adopted objectives.
 - Objective for intra-rack and active cable applications
 - This was not listed separately in the adopted objectives.
 - Backwards compatibility is not needed, but lowest cost is needed.
 - A PMD capable of 50 m reach on OM4 fiber may be uncompetitive with a PMD developed specifically for very short reach, such as 10 - 20 m.
 - This contribution explores some of the tradeoffs for MMF reaches shorter than the adopted objective(s).

Background-2

- [parsons_100GSR_adhoc_01_021320.pdf](#) showed that a 30 m reach on OM3 could be achieved with a single PMD also capable of 50 m on OM4 fiber.
 - Required VCSEL bandwidth is 23.3 to 23.8 GHz for OM3/OM4 respectively
 - Overall signal bandwidth at receiver is 21.25 GHz [cascade of BW_{VCSEL} , $BW_{\text{Chromatic Dispersion}}$, and $BW_{\text{Modal Dispersion}}$]
- [king_3cm_adhoc_01_062818.pdf](#) included details of the calculation of effective bandwidth for MMF, based on the 10GE spreadsheet model [10GEPBud3_1_16a.xls](#) and TIA worst case OM3/OM4 EMB values versus wavelength.
- This contribution uses the same methodology to understand the reach limitations and VCSEL bandwidth requirements for 850 nm and 940 nm VCSELs on OM3/OM4/OM5 fiber with minimum EMB and CD characteristics as specified in IEC 60793-2-10.

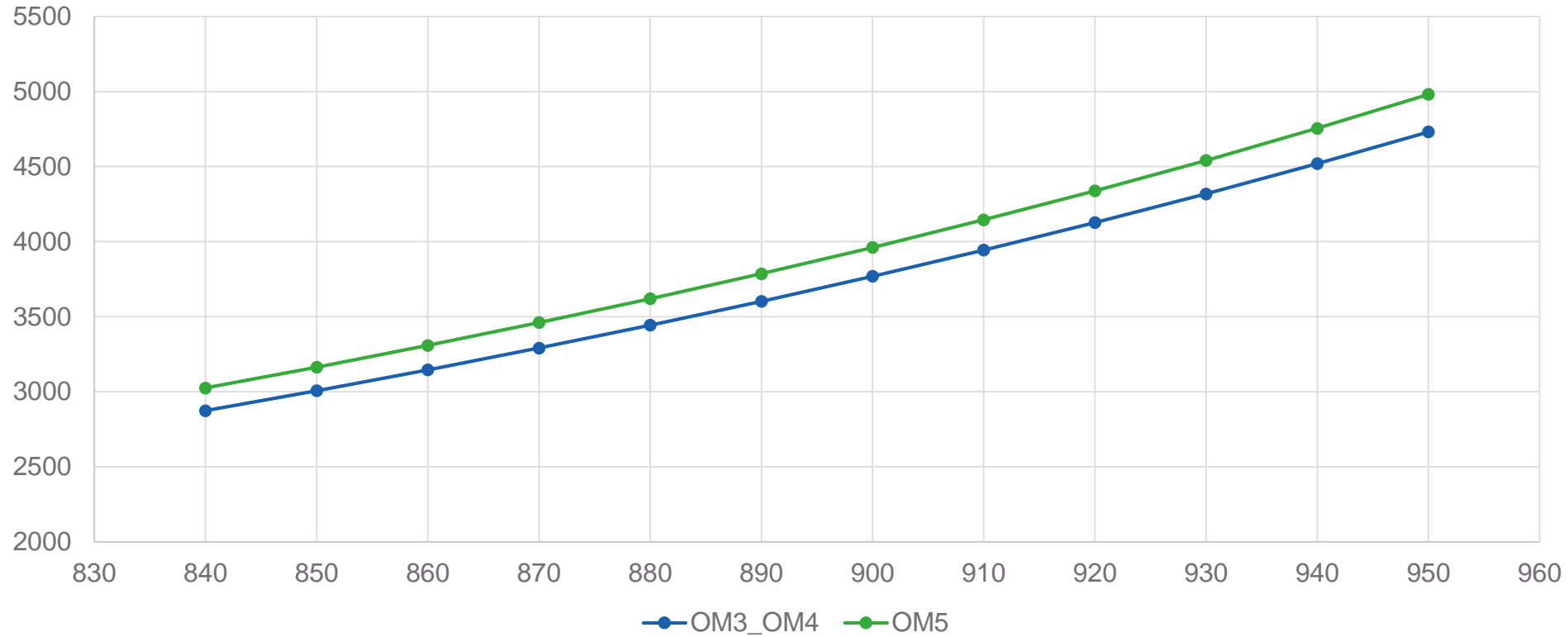
IEC worst case EMB-length product for OM3, OM4 and OM5

Minimum effective modal bandwidth-length product (EMB) versus wavelength per IEC 60793-2-10



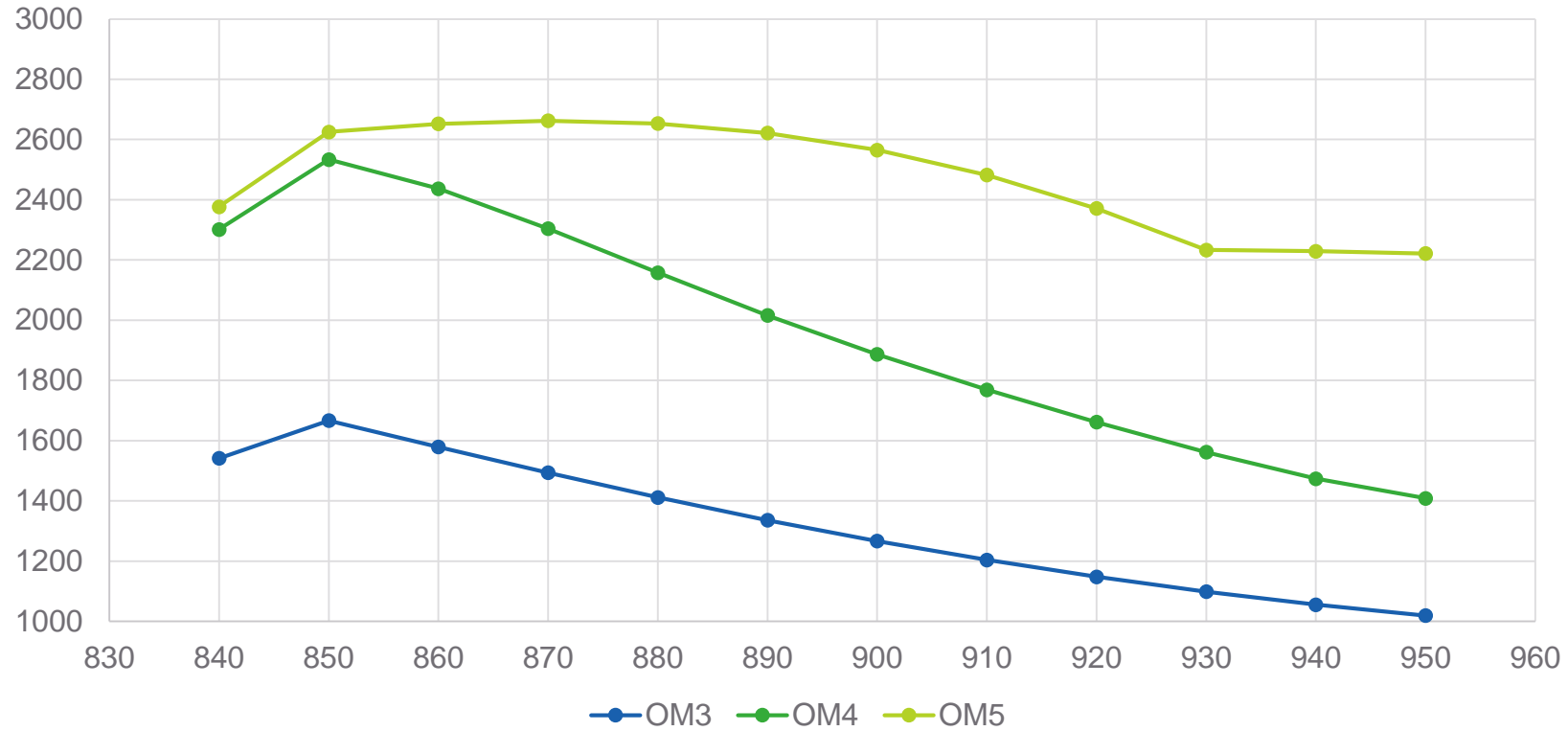
BW_{CD}-distance product versus wavelength

BWcd (min) versus wavelength at 0.6 nm spectral width per IEEE
10GE spreadsheet model and IEC 60793-2-10



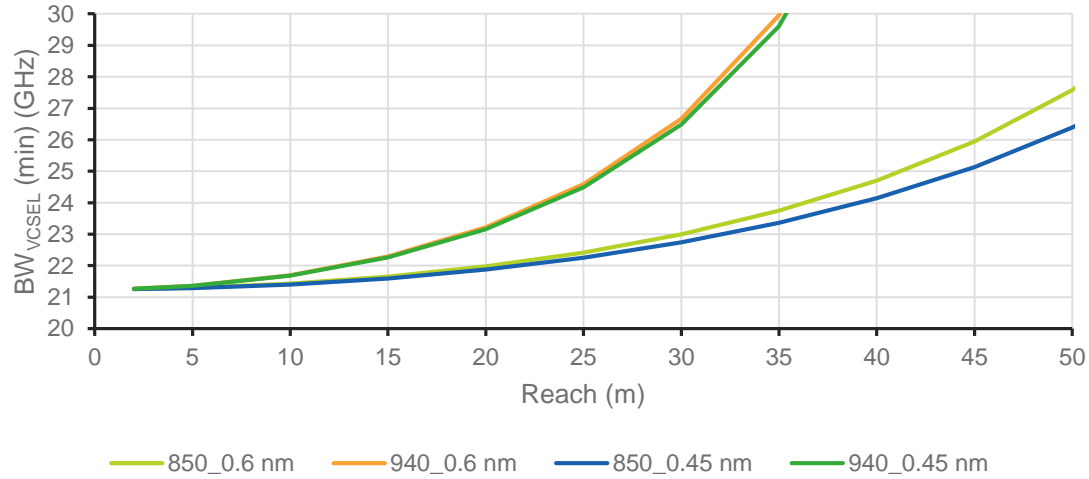
BW_{eff} – distance product versus wavelength

BW_{eff} (min) versus wavelength at 0.6 nm spectral width per 10GE spreadsheet model

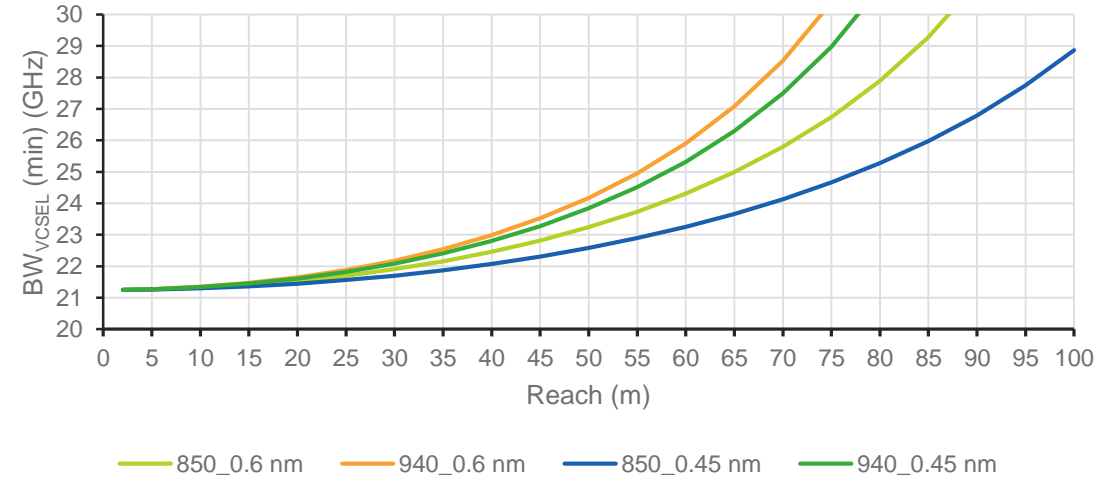


BW_{VCSEL} versus reach and spectral width

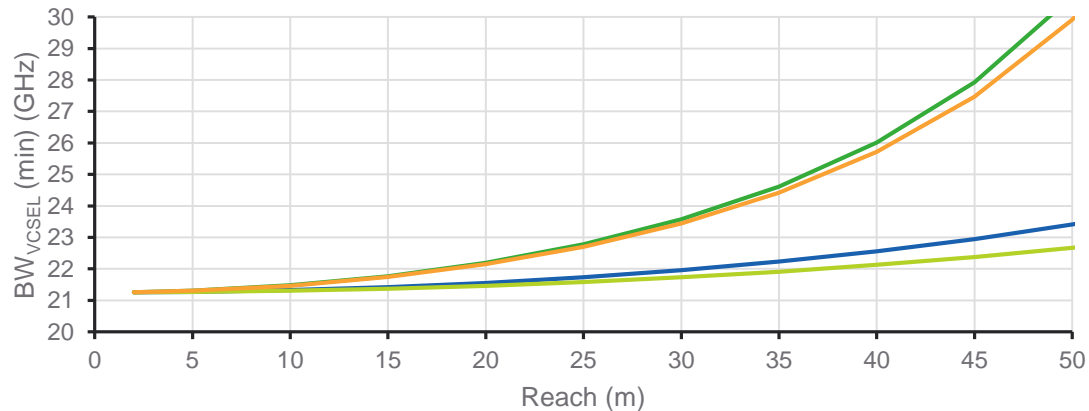
Required VCSEL BW versus reach for OM3 fiber, 0.45 or 0.6 nm spectral width



Required VCSEL BW versus reach for OM5 fiber, 0.45 or 0.6 nm spectral width



Required VCSEL BW versus reach for OM4 fiber, 0.45 or 0.6 nm spectral width



- 940 nm VCSELs require higher BW for all classes of 850-optimized MMF
- For VCSEL BW of 23 GHz, the reach differences are minimal

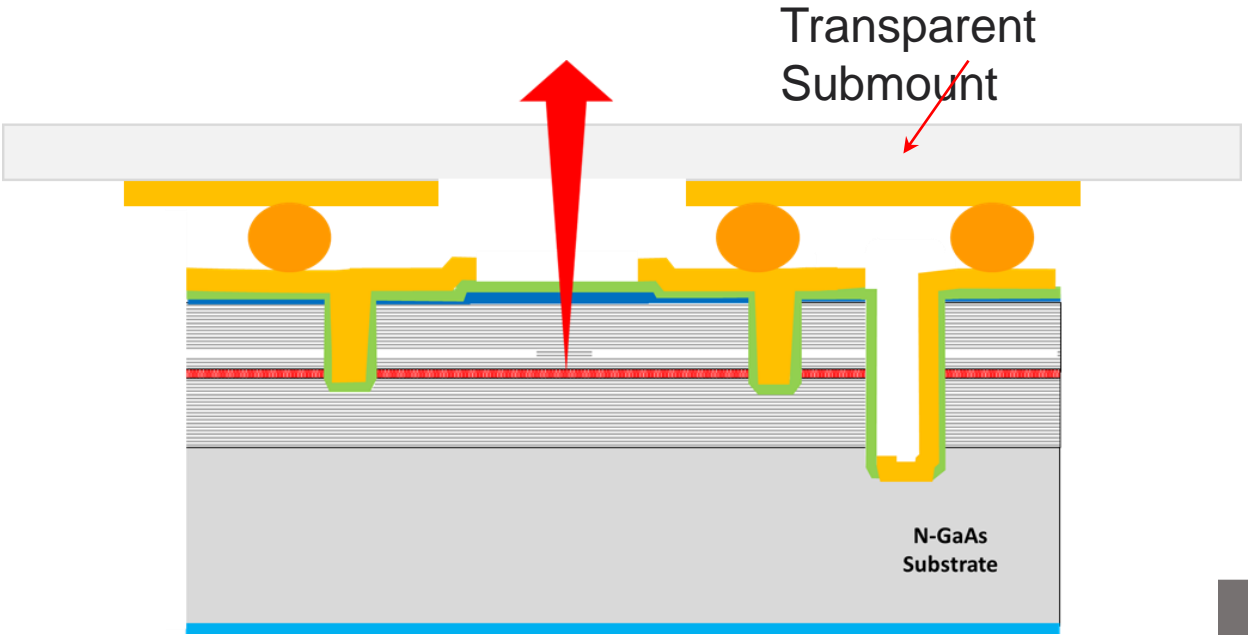
Why 940 nm and not 980 or some other wavelength?

- 940 nm is used for 3D sensing (3DS) because:
 - There is a dip in atmospheric transmission at 940 nm which means less solar background vs 980 nm.
 - For low speeds, it is detectable by silicon PDs.
 - No distracting “red glow” as with 850 nm VCSELs.
- 940 nm has reached a lower cost point than 850 nm VCSELs
 - > 500 million array chips, each with 100’s of VCSELs shipped to date
 - 6-inch wafers used for fabrication
- A 50 Gbd PAM4 VCSEL is a different device design to the 3DS array
 - 3DS is high-power & high-efficiency to minimize battery use
 - 3DS operates at 10’s to 100’s of MHz, whereas datacom requires 10’s of GHz.
 - Spectral width is < 0.45 nm over temperature.
 - The datacom chip reduces parasitic capacitance & inductance by having very small bond-pads to achieve high frequency operation.

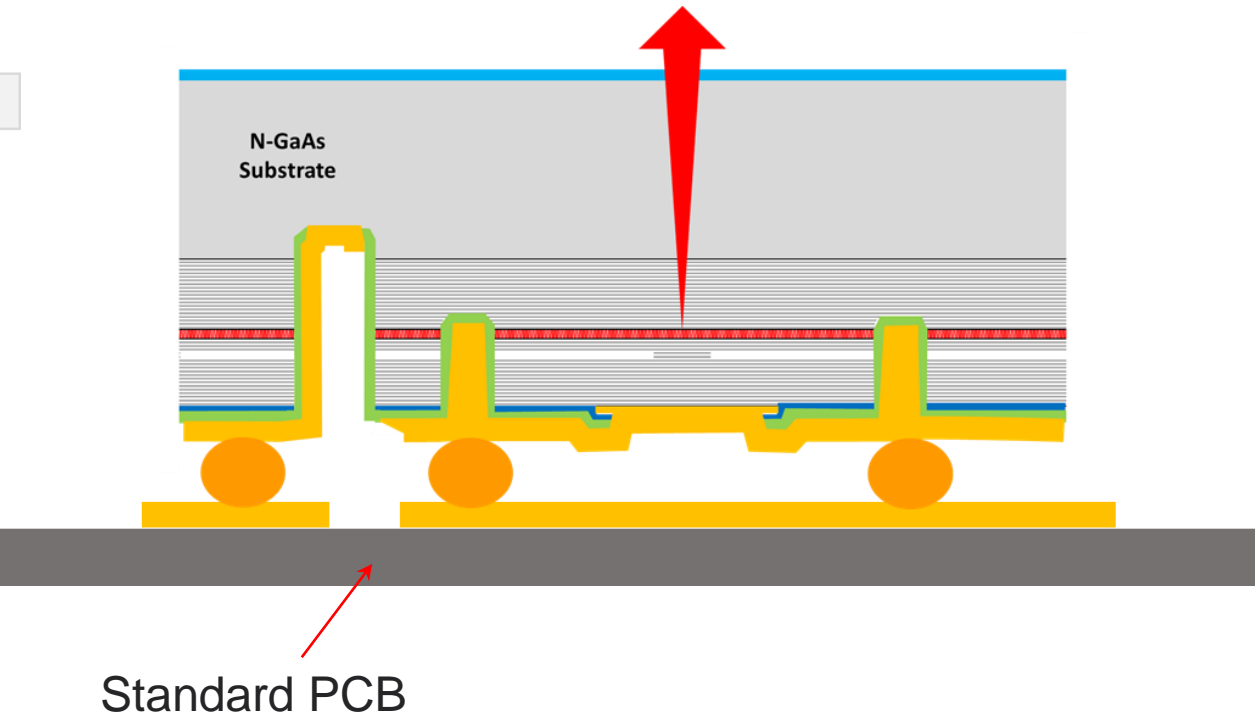
Flip-Chip VCSEL Attach – 850nm vs 940nm VCSEL

- 1. 850nm flip-chip attach requires expensive transparent submount to allow light to pass through
- 2. 940nm flip-chip attach can use standard PCB, since light can pass through the bottom of the substrate

Top Emitting



Bottom Emitting



Advantages of bottom-emitting (BE) VCSEL

- Flip-chip enables the required overall BW (driver + VCSEL chip) of ~ 23 GHz
- BE VCSEL can be flip-chip attached directly on a sub mount or PCB with good heatsinking and matched impedance lines from the driver IC.
- Can electrically pump the entire VCSEL aperture because no light needs to exit on the electrical side of the VCSEL.
- 850 nm flip-chip requires a transparent sub mount in the package. This makes heat sinking more challenging since transparent sub mounts (quartz usually) have poor thermal conductivity compared to copper or gold.

Recommendations

- Add an objective for intra-rack and active cable applications
 - Define a physical layer specification that supports 100 Gb/s operation over 1 pair of MMF with lengths of up to at least 20 m.
- Consider adding an interoperability objective between the 20 m and 50 m PMDs
 - Requires receivers of both to work over the superset of wavelengths and at the same power levels.

Thank you

